


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STSFA110DFSPL02	23ZW*D3HEYYY	A	9996	21-09-2021
	Amount	UoM	Unit type	ST ECOPACK Grade
	12.40	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	2x3x0.6	8	No lead	
Comment	Package : ZW UDFPN 2x3x0.6 8L 0.5MM PITCH 7558452			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-8th July 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	23ZW*D3HEYYY				7000002.0	1000001.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.883	mg	supplier	die	Silicon (Si)	7440-21-3		0.808	mg	915062	65161
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	10193	726
				supplier	metallization	Copper (Cu)	7440-50-8		0.030	mg	33975	2419
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.011	mg	12458	887
				supplier	Passivation	Silicon Nitride	12033-89-5		0.006	mg	6795	484
LEADFRAME (C7025RuPPF)	M-011 Other inorganic materials	6.153	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	21518	1532
				supplier	ALLOY	Copper (Cu)	7440-50-8		5.919	mg	961970	477339
				supplier	ALLOY	Nickel (Ni)	7440-02-0		0.185	mg	30067	14919
				supplier	ALLOY	Silicon (Si)	7440-21-3		0.040	mg	6501	3226
				supplier	ALLOY	Magnesium (Mg)	7439-95-4		0.009	mg	1463	726
LEADFRAME (C7025RuPPF) Coating	M-011 Other inorganic materials	0.140	mg	supplier	COATING	Nickel (Ni)	7440-02-0		0.136	mg	974910	10968
				supplier	COATING	Palladium (Pd)	7440-05-3		0.003	mg	21505	242
				supplier	COATING	Gold (Au)	7440-57-5		0.000	mg	2151	24
				supplier	COATING	Silver (Ag)	7440-22-4		0.000	mg	1434	16
				supplier	GLUE	Resin	Proprietary		0.041	mg	445652	3306
GLUE (ATB-F125E)	M-011 Other inorganic materials	0.092	mg	supplier	GLUE	Silica	7631-86-9		0.051	mg	554348	4113
				supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.050	mg	1000000	4032
BONDING WIRE	M-011 Other inorganic materials	0.050	mg	supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		0.459	mg	90568	36994
				supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		4.351	mg	859106	350919
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		0.229	mg	45291	18500
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.026	mg	5035	2056
				supplier	COATING	Nickel (Ni)	7440-02-0		0.015	mg	857143	1210
EXTERNAL PLATING	M-011 Other inorganic materials	0.018	mg	supplier	COATING	Palladium (Pd)	7440-05-3		0.001	mg	57143	81
				supplier	COATING	Gold (Au)	7440-57-5		0.001	mg	57143	81
				supplier	COATING	Silver (Ag)	7440-22-4		0.001	mg	28571	40

